



Package Material Declaration Sheet (MDS)

Mfg. Part	AS7C1026B-XXJCN
PackageWeight	1938.4 mg

Approved	Prepared
Dick	Ram

No.	Part Name	Material Name	Component wt(mg)	Material Content (Element)	CAS Number	Element Wt ^(A) (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	CDA 194	401.4000	Copper	7440-50-8	97.0000	389.4000	20.08873	200887.33
				Iron	7439-89-6	2.1000	8.4000	0.43335	4333.47
				Phosphorus	7723-14-0	0.0150	0.1000	0.00516	51.59
				Zinc	7440-66-6	0.0500	0.2000	0.01032	103.18
				Lead	7439-92-1	0.0020	0.0000	0.00000	0.00
				Silver	7440-22-4	0.8330	3.3000	0.17024	1702.43
2	Die attach material	EN-4900G*	1.5000	Acrylic Resin	Trade Secret	8.5000	0.1275	0.00658	65.78
				Polybutadiene derivative	Trade Secret	5.5000	0.0825	0.00426	42.56
				Butadiene copolymer	Trade Secret	1.0000	0.0150	0.00077	7.74
				Epoxy Resin	Trade Secret	2.5000	0.0375	0.00193	19.35
				Acrylate	Trade Secret	5.5000	0.0825	0.00426	42.56
				Peroxide	Trade Secret	0.5000	0.0075	0.00039	3.87
				Additive	Trade Secret	1.0000	0.0150	0.00077	7.74
				Silver (Metal Powder)	7440-22-4	75.5000	1.1325	0.05842	584.24
3	Gold Wire	Gold	9.0000	Au	7440-57-5	99.9950	8.9996	0.46428	4642.77
				Ag	7440-57-5	0.0010	0.0001	0.00000	0.05
				Fe	7440-57-5	0.0003	0.0000	0.00000	0.01
				Cu	7440-57-5	0.0003	0.0000	0.00000	0.01
				Impurities	7440-57-5	0.0035	0.0003	0.00002	0.16
4	Tin Plate	Pure Tin	11.2000	Sn	7440-31-5	100.0000	11.2000	0.57780	5777.96
5	Mold Compound	CEL-9240	1515.0000	Epoxy Resin-1	Trade Secret	3.2500	49.2375	2.54011	25401.10
				Epoxy Resin-2	Trade Secret	3.0000	45.4500	2.34472	23447.17
				Phenol Resin	Trade Secret	4.5000	68.1750	3.51708	35170.76
				Carbon Black	1333-86-4	0.2000	3.0300	0.15631	1563.14
				Silica	60676-86-0	88.0000	1333.2000	68.77837	687783.74
				Others		1.0500	15.9075	0.82065	8206.51
6	Die	Silicon Chip	0.3000	Si	7440-21-3	100.0000	0.3000	0.01548	154.77
Total unit weight =			1938.400						

Note:

- (A) Element Wt Composition is derived from MSDS and/or material C of C from Vendors.
- (B) Wt of silver spotted on leadframe is estimated.
- (C) Component Weight based on assembly of generic parts.